



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD031N03L G		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA000638990						
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		317.83 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.247	0.71	0.71	7069	7069
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		135	
	non noble metal	iron	7439-89-6	0.143	0.05		451	
	non noble metal	copper	7440-50-8	143.098	45.01	45.07	450233	450819
	non noble metal	aluminium	7429-90-5	3.786	1.19	1.19	11911	11911
wire	non noble metal	aluminium	7429-90-5	3.786	1.19	1.19	11911	11911
encapsulation	organic material	carbon black	1333-86-4	0.315	0.10		992	
	plastics	epoxy resin	-	19.035	5.99		59889	
	inorganic material	silicondioxide	60676-86-0	123.983	39.01	45.10	390092	450973
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11767	11767
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	272	273
solder	non noble metal	tin	7440-31-5	0.043	0.01		135	
	noble metal	silver	7440-22-4	0.054	0.02		169	
	non noble metal	lead	7439-92-1	2.056	0.65	0.68	6468	6772
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60338	60416
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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